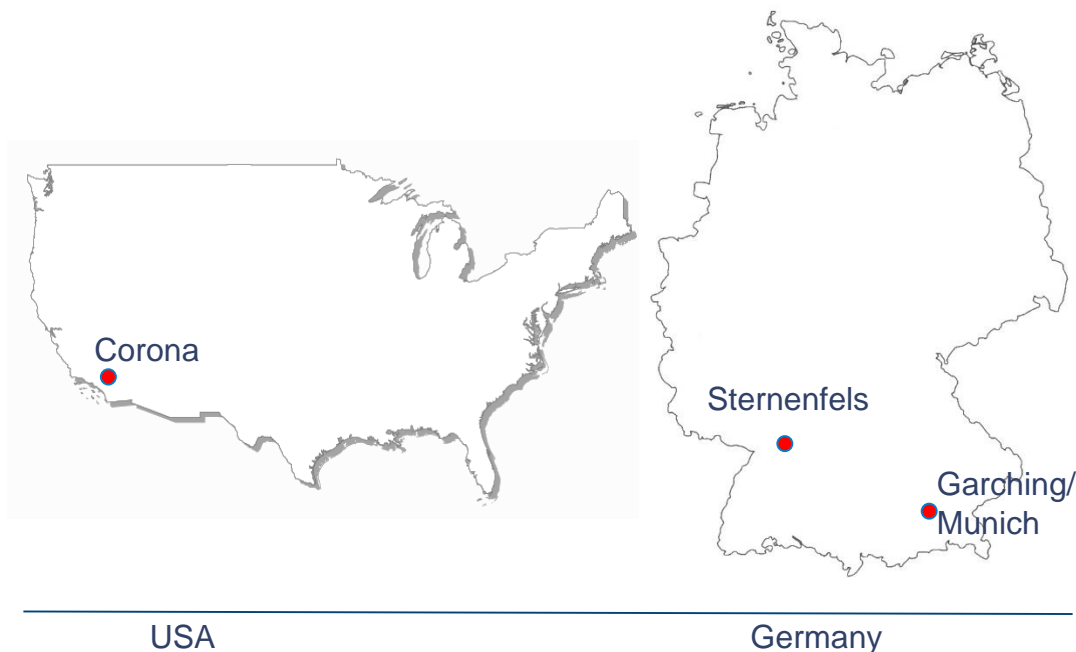


SUSS MICROTEC INVESTOR PRESENTATION

February 2018



- + International high tech equipment provider for the semiconductor mid- and backend industry
- + All major chip manufacturers are clients of ours
- + Global customer base with focus on Asia
- + Production at two major sites in Germany and one in the USA



Highlights FY 2017 (preliminary numbers)

- + Order entry > € 200 million
- + Sales ~ € 166 million
- + EBIT ~ 14 million
- + EBIT-margin > 8%

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 33.7 € million

Sales 25.4 € million

Employees 102

EMEA

Order Entry 38.1 € million

Sales 43.1 € million

Employees 469

ASIA

Order Entry 89.3 € million

Sales 109.0 € million

Employees 140



*Figures refer to the fiscal year 2016

OUR PRODUCT PORTFOLIO

Frontend

Mid- and Backend

Photomask Equipment

Photomask
Cleaning



MaskTrackPro

Lithography

Laser Processing
Equipment



ELP300

Exposure
Systems



Mask Aligner
MA200/300 Gen2



Projection Scanner
DSC300 Gen2

Coaters and
Developers



ACS300 Gen2

Bonder

Wafer Bonding
Equipment



XBC300 Gen2



XB8

WE SUPPORT TECHNOLOGICAL CHANGE

Telecommunications



- Communication
- Mobility
- Networks

Data Processing



- Data processing
- Mobility
- Digitization
- Smart factory

Automotive



- Safety
- Comfort
- Energy efficiency
- Autonomous driving

Portable electronic products are driving component packaging towards new packaging technologies for integrating multiple functions (e.g. memory, analog and passive components: SiP)



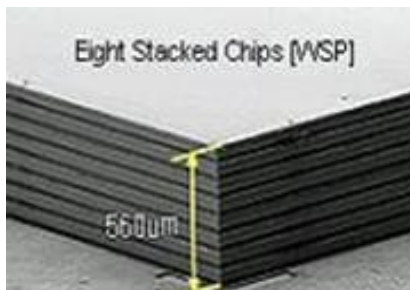
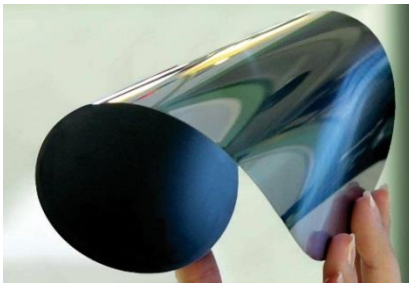
+ **Fan Out Wafer Level Packaging (FOWLP)**

+ **3D- Integration with Thru Silicon Vias (TSV)**

Allows for:

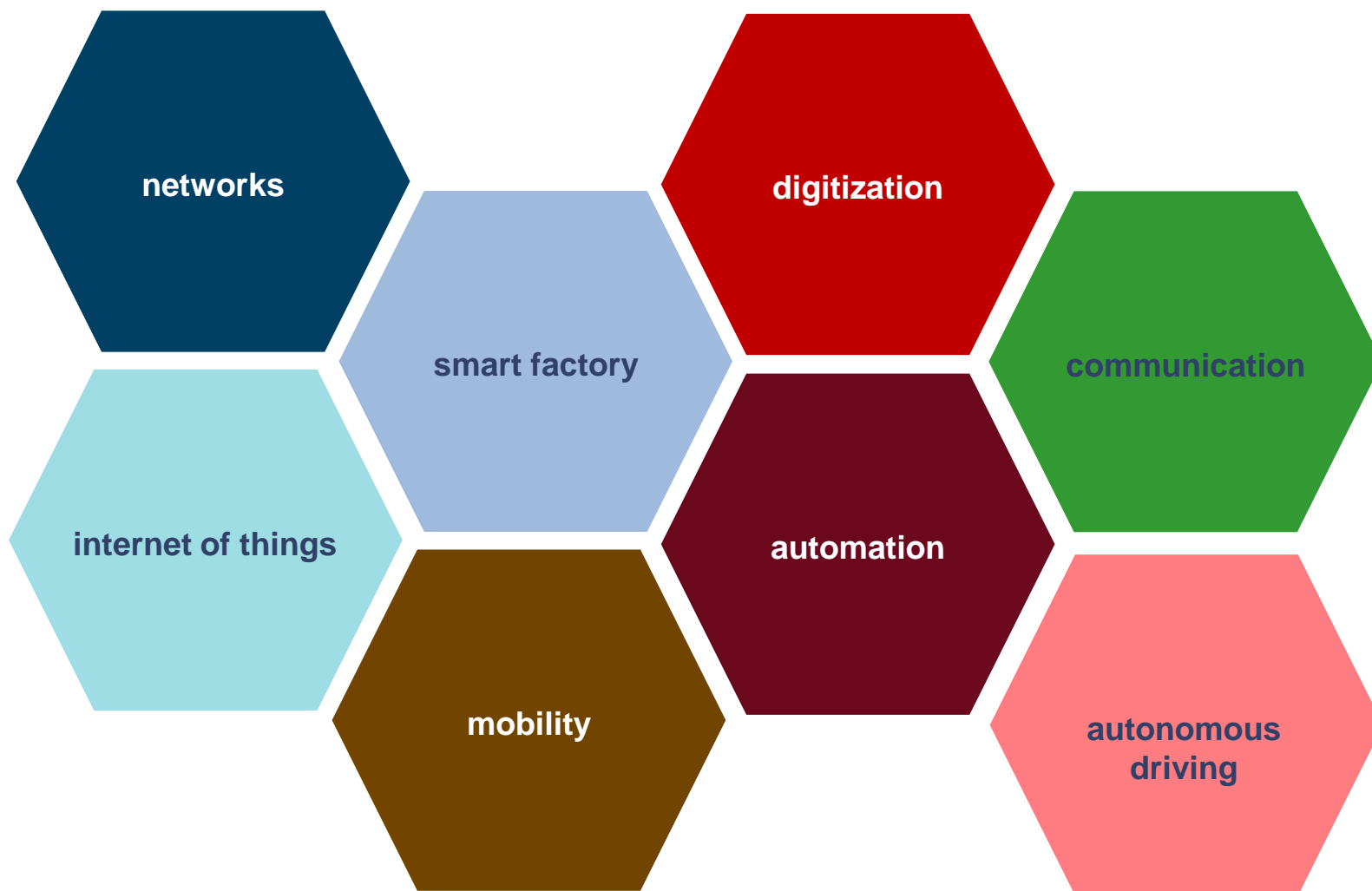
- **Smaller form factors**
- **Multi-die package / SiP**
- **Increased I/O density** (Fine line and space (L/S))
- **Providing high capacity and high bandwidth packages**

This trend will continue.



- + **Since the early 1990s, advanced packaging methods have enabled smaller chip packages:**
 - SUSS was one of the drivers in the introduction of advanced packaging in the 1990s
 - SUSS was a founding member of SECAP (Semiconductor Equipment Consortium for Advanced Packaging)
 - SECAP supported the transition from "wire bonding" to "flip chip bonding"
- + **Today, SUSS supports the transition from 2D to 2.5D and finally to 3D TSV (Thru Silicon Via)**
 - SUSS works with the leading users of 3D TSV technology
 - First pilot lines are installed and will be further optimized
 - SUSS is one of the leading equipment suppliers for this growth area
- + **„Thin wafer handling “ and „temporary bonding“ are major elements of 3D stacking**

GROWTH DRIVERS ARE INTACT



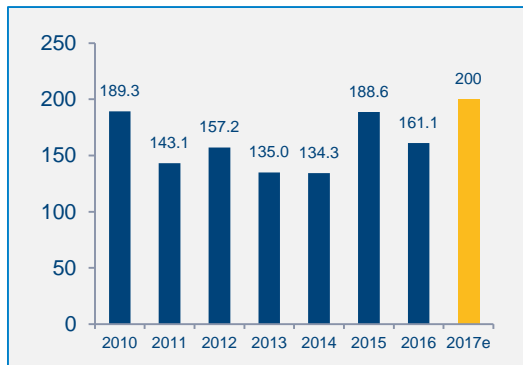
PRELIMINARY KEY GROUP FIGURES AT A GLANCE FY 2015 - 2017

in € million	delta 2017/2016	2017	2016	2015
Order Intake	+24%	200	161.1	188.6
Order Backlog 12/31	+31%	135	101.5	117.6
Revenue	-6%	166	177.6	148.5
EBIT	+25%	14	11.1	5.0
<i>EBIT in % of Sales</i>	<i>+>2%pts</i>	<i>>8%</i>	<i>6.3%</i>	<i>3.4%</i>
Earnings after tax			5.0	0.2
EPS in €			0.26	0.01
Free Cash Flow*			-9.1	1.3
Net Cash			31.1	40.0
Employees 12/31			711	698

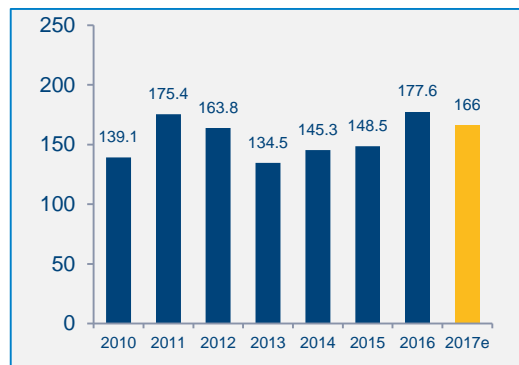
*before consideration of transactions with interest-bearing securities

LONG TERM BUSINESS DEVELOPMENT

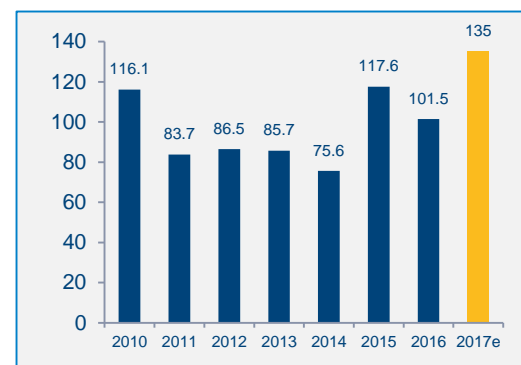
Order Entry in € million



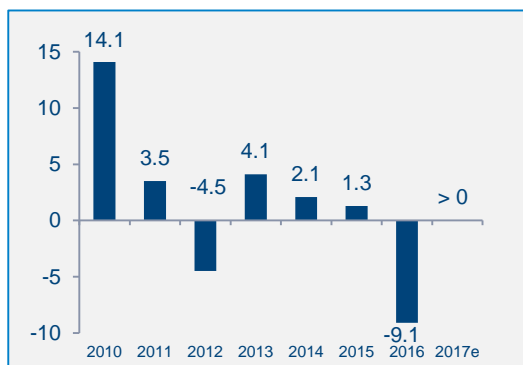
Sales in € million



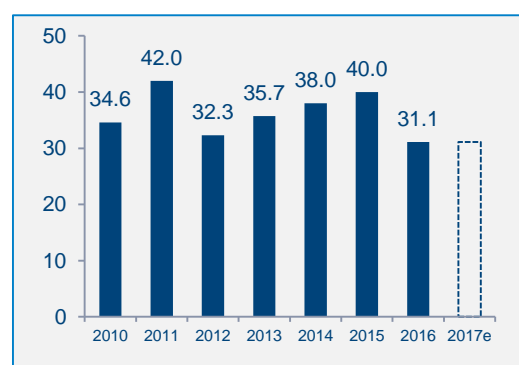
Order Backlog in € million



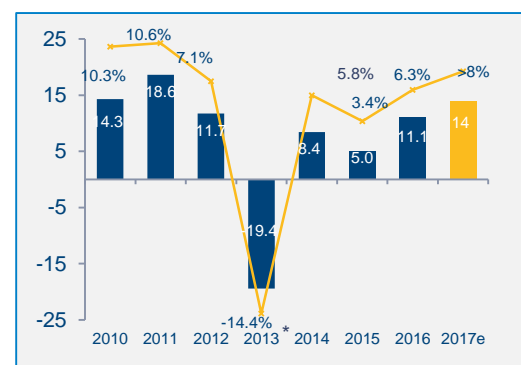
Free Cash Flow** in € million



Net Cash in € million



EBIT in € million

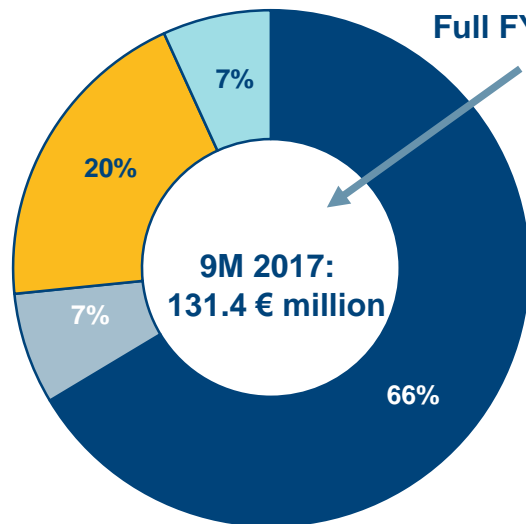


* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

** FCF = operating CF + CF from investments + changes in securities holdings

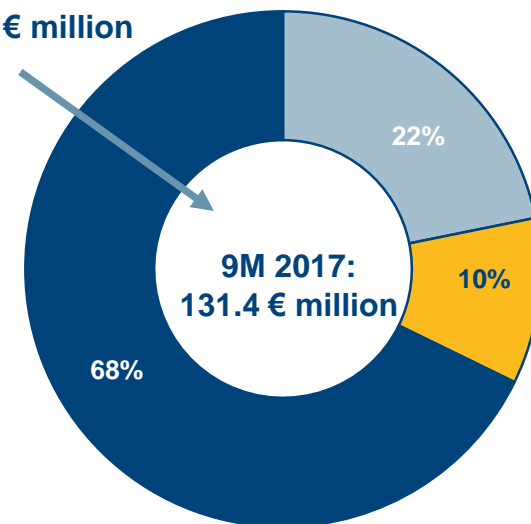
ORDER ENTRY BY SEGMENT AND REGION IN 9M 2017

Segments



- Lithography
- Fotomask Equipment
- Bonder
- Others

Regions



- Europe
- North America
- Asia/Pacific

SEGMENTS, ORDER ENTRY AND SALES 9M/FY 2017

Divisions

Photomask Equipment

Photomask Cleaning
Equipment

9M
2017

Order Entry: 9.2 € million
Sales: 16.7 € million
EBIT: 5.1 € million

Lithography

Laser
Processing
Equipment

Exposure
Systems

Coaters and
Developers

Order Entry: 87.2 € million
Sales: 74.8 € million
EBIT: 1.7 € million

Bonder

Wafer Bonding
Equipment

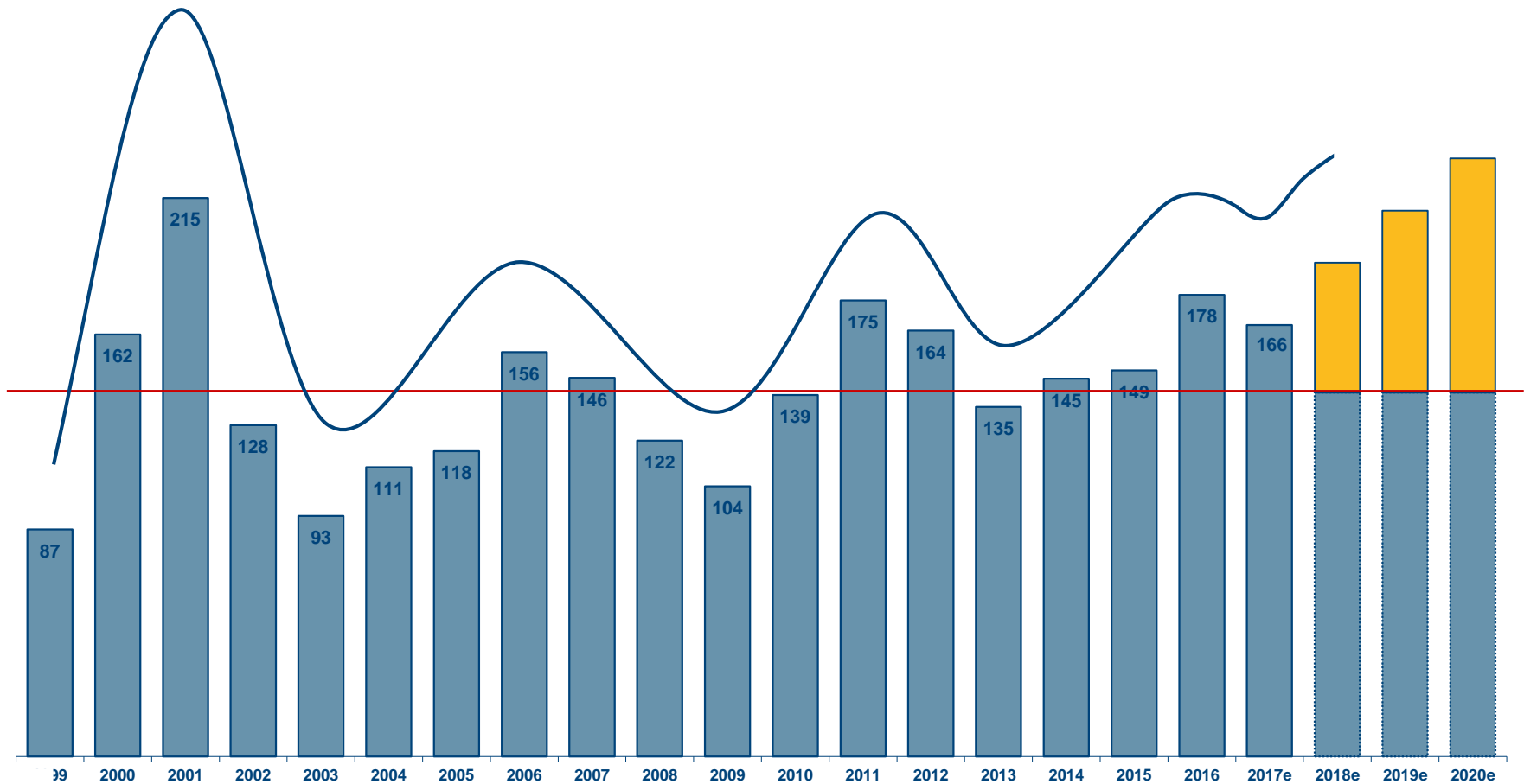
Order Entry: 26.0 € million
Sales: 12.9 € million
EBIT: 1.8 € million

SÜSS MicroTec Group FY 2017

Order Entry: ~ 200 € million
Sales: ~ 166 € million
EBIT: ~ 14 € million
EBIT margin: > 8%

* Including Others

LONG TERM SALES DEVELOPMENT IN € MILLION



Average sales level 1999 – 2016: appr. € 140 million

OUTLOOK 2017 – PRELIMINARY KEY FIGURES 2017



+ Fiscal year 2017:

- Order entry ~ € 200 million**
- Sales ~ € 166 million**
- EBIT ~ € 14 million**
- EBIT-margin > 8%**



- + Gartner expects the semiconductor market to grow by 7.5% in 2018 after 22.2% in 2017
- + This would mark a new record sales level of USD 451 billion for the semiconductor industry in 2018
- + Market growth is driven by automotive and industrial applications as well as memory chips and the internet of things
- + Semi expects a market growth of +7.5 % in the semiconductor-equipment industry in 2018 after 35.6% in 2017
- + Wafer fab equipment incl. Wafer-level packaging grew by +17.9% in 2017 (according to Gartner)
- + Yole expects the MEMS-market to grow by +16.7% (CAGR) from 2016 to 2022(unit growth)



WE ARE SÜSS MICROTEC – BACK UP

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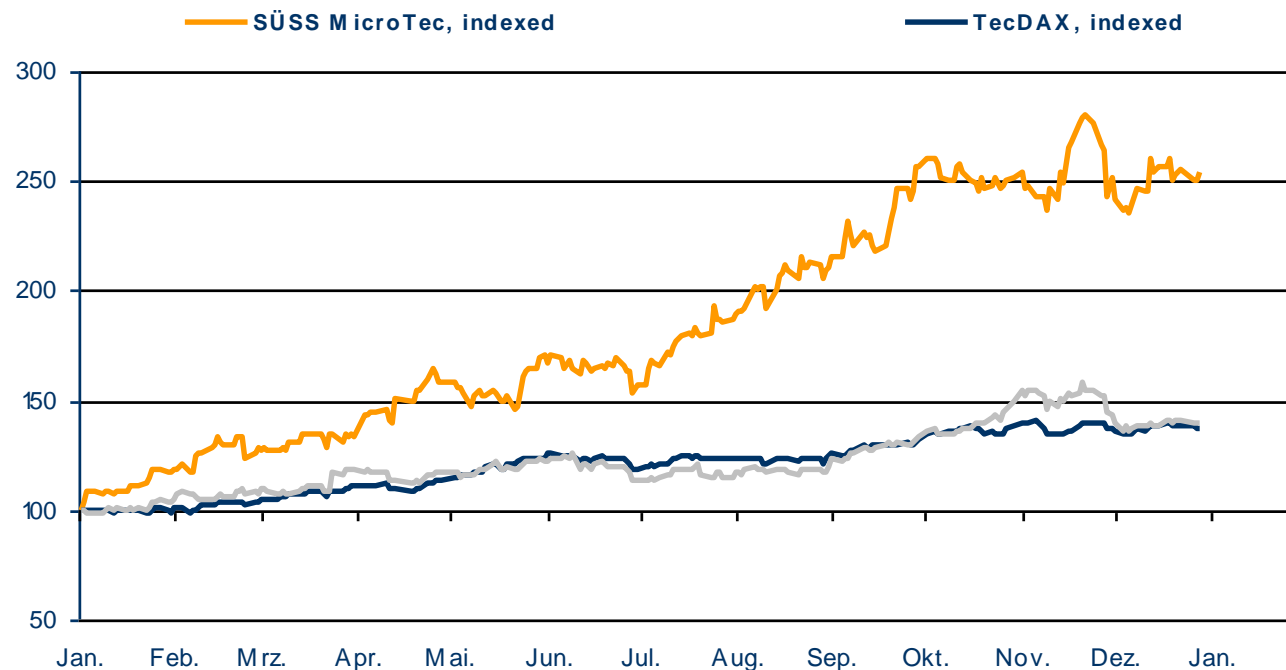
SÜSS MicroTec SE
Schleissheimer Strasse 90
85748 Garching
Germany
www.suss.com

Financial Calendar 2018

Quarterly Report 2018	3 May
Annual General Meeting 2018, Munich	6 Jun
Interim Report 2018	3 Aug
Nine-month Report 2018	7 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2017: 6.54 €)



Major Shareholders > 3%:

Universal-Investment
Kempen Oranje
Henderson Global Investors
Lupus Alpha
Luxunion
Hansainvest
Dimensional Funds

Average daily trading volume January 2016 – January 2018: ~ 120.000

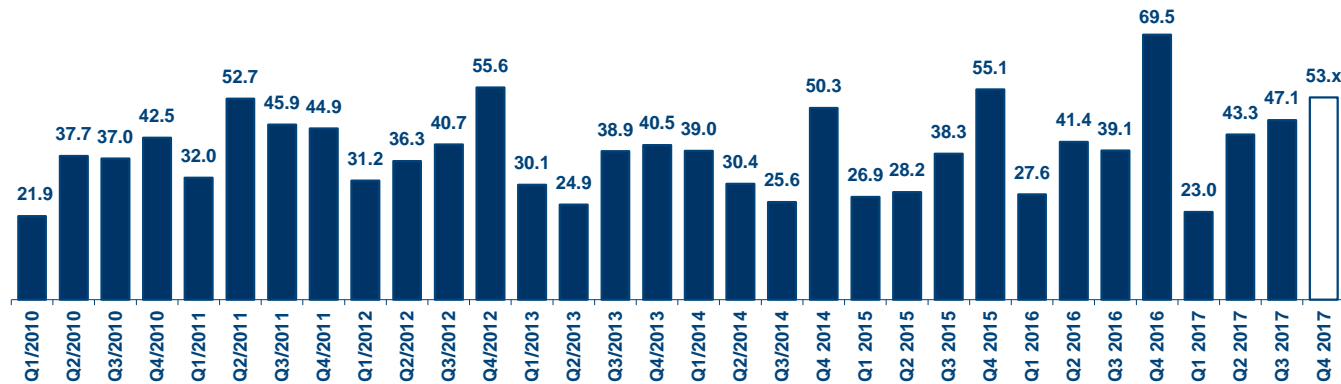
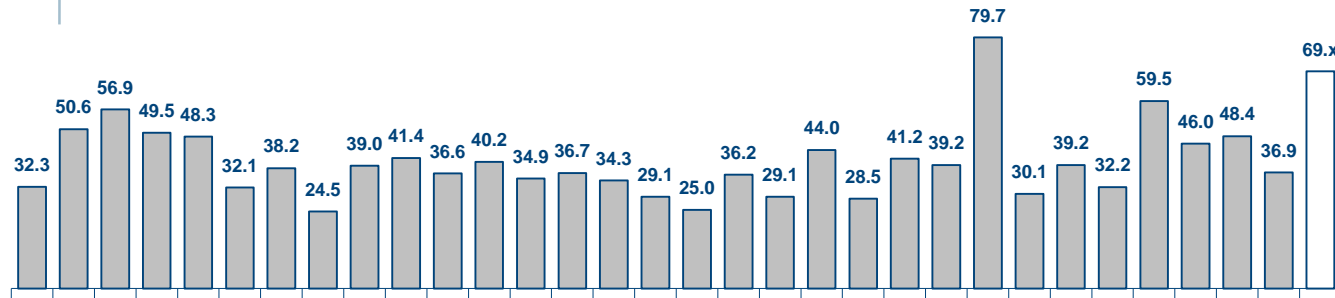
9M KEY GROUP FIGURES AT A GLANCE

in € million	Q3 2017	Q3 2016	Delta
Order Intake	36.9	32.2	+14.6%
Order Backlog 9/30	--	--	--
Revenue	47.1	39.1	+20.5%
EBIT	7.0	1.0	>100%
<i>EBIT in % of Sales</i>	<i>14.9%</i>	<i>2.6%</i>	12.3%pts
Earnings after tax	4.5	-0.2	--
EPS in €	0.24	-0.01	--
Free Cash Flow*	6.3	-1.7	--
Net Cash	--	--	--
Employees 9/30	--	--	--

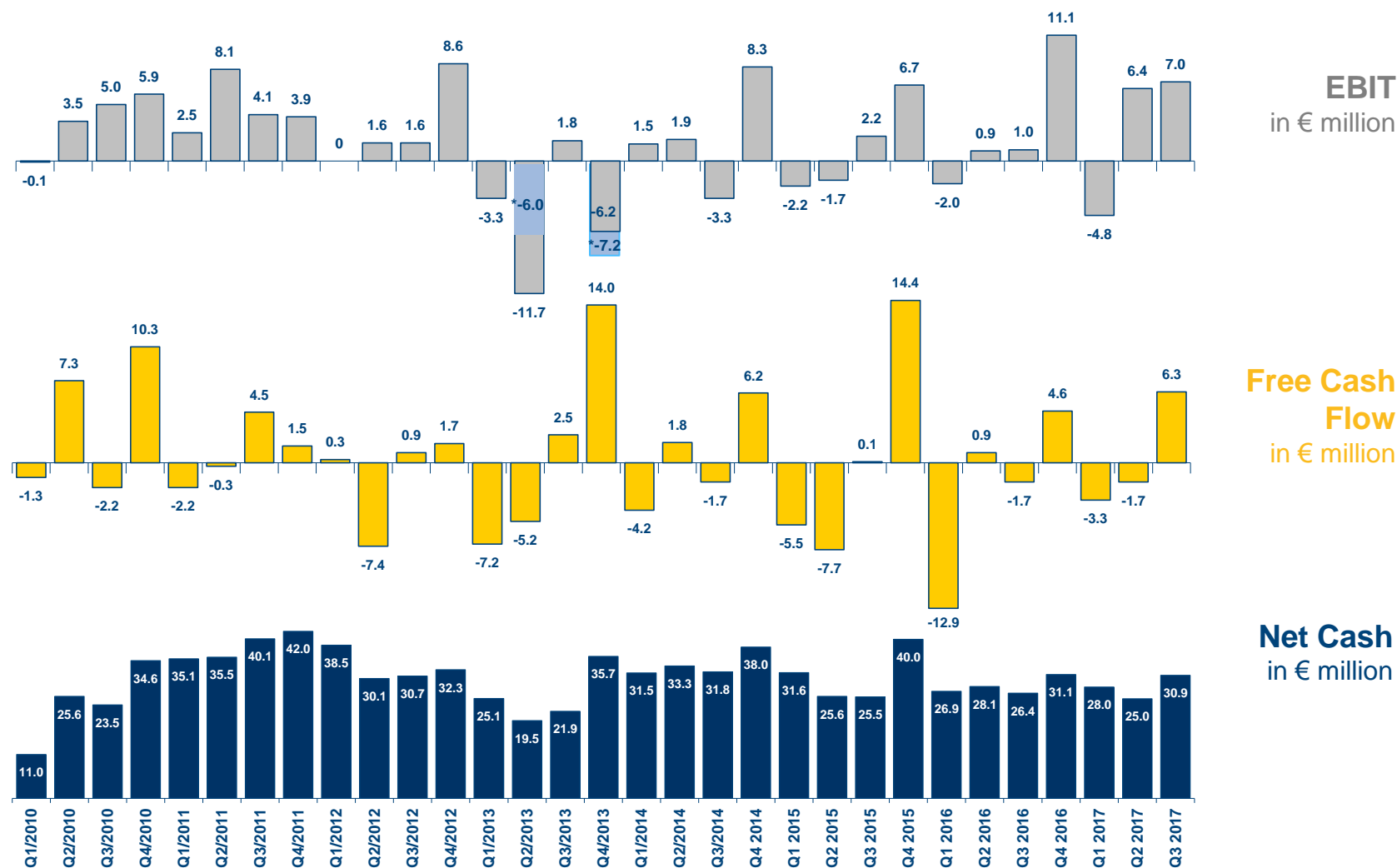
9M 2017	9M 2016
131.4	101.5
117.7	110.9
113.4	108.1
8.6	0.0
7.6%	0.0%
3.8	-3.3
0.20	-0.17
0.7	-13.7
30.9	26.4
762	720

*before consideration of transactions with interest-bearing securities

LONG TERM BUSINESS DEVELOPMENT BY QUARTER

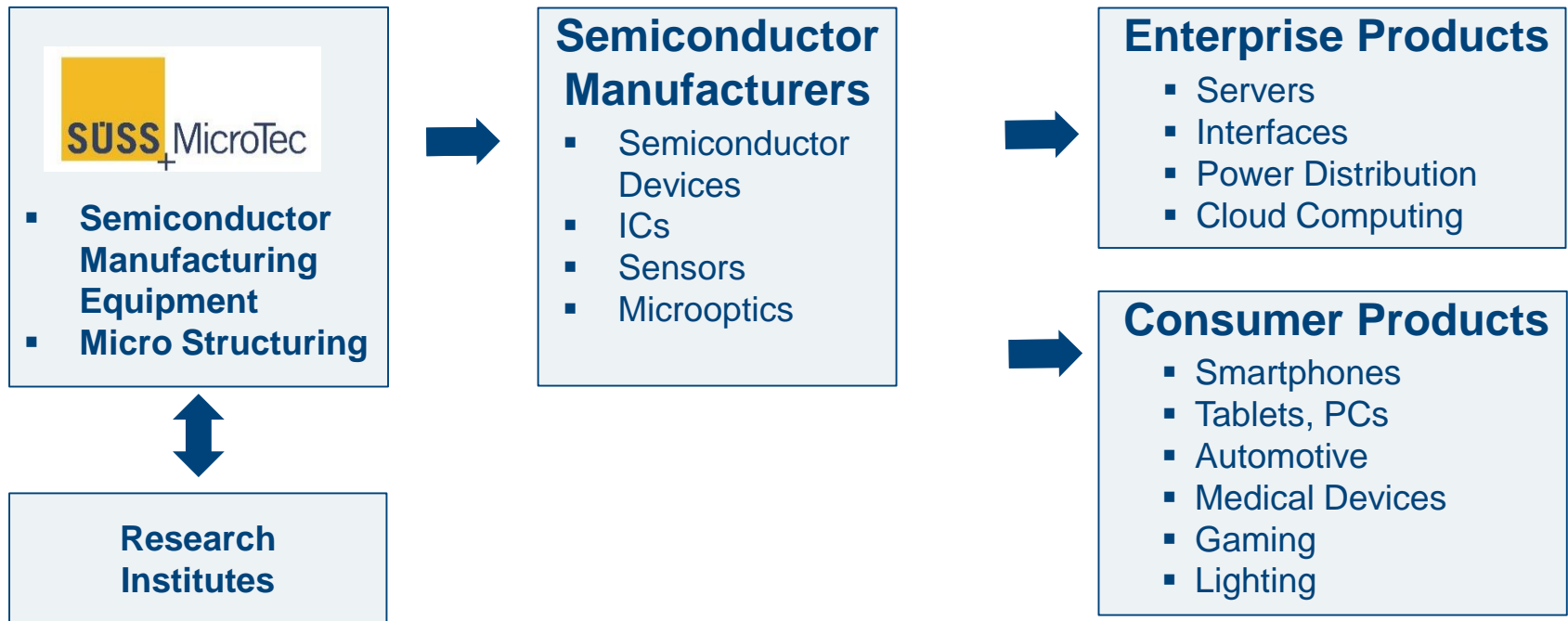


EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from restructuring the product line permanent bonding

SUSS MICROTEC IN THE VALUE CHAIN

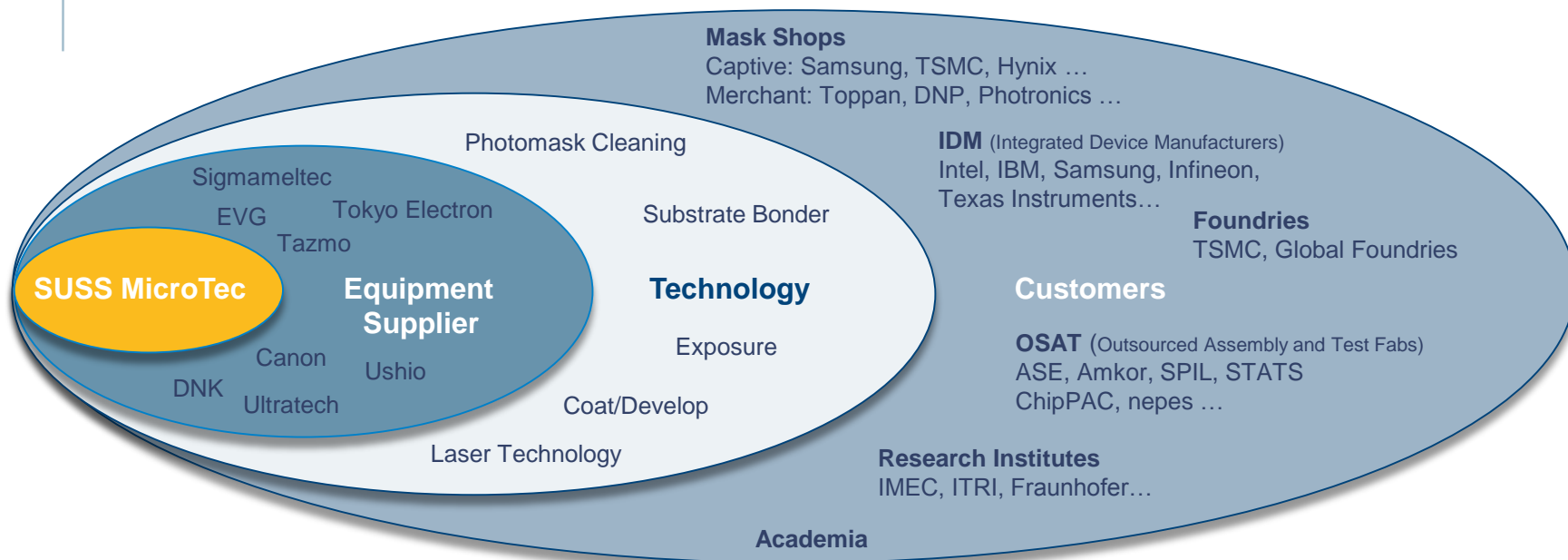


+ SUSS MicroTec:

- Key player in leading edge semiconductor manufacturing equipment
- Developer of highly innovative process solutions

+ Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec's equipment

MAIN COMPETITORS AND PEER GROUP



Peer Group

BE Semiconductor:

equipment for leadframe, substrate and WLP applications (die attach, wire-bonding, plating), target markets include electronics, computer, automotive, industrial, LED and solar energy

Veeco/UTEC:

steppers for the semiconductor market, advanced packaging, nanotechnology, laser processing (LSA)

Kulicke & Soffa:

design and manufacture of equipment for semiconductor, LED and electronic assembly (wire-bonding, advanced packaging)

Rudolph Tech:

equipment and software solutions for macro defect inspection, probe card test and analysis, thin film metrology, advanced packaging lithography systems (steppers)

EV Group:

equipment for wafer-bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection for the target markets: advanced packaging, compound semiconductor and silicon-based power devices, MEMS, nanotechnology and SOI

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SÜSS MicroTec SE and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SÜSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SÜSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.